

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|---|---------------------------------|------------------|
| 1 | 7 | ((("5690050") or ("5944899") or ("5735993") or ("6177646") or ("6095083") or ("5922223") or ("6077384")).PN. | USPAT; US-PGPUB | 2002/05/10 13:06 |
| - | 412 | (118/723i).CCLS. | USPAT; US-PGPUB | 2002/05/10 13:06 |
| - | 240 | (156/345.48).CCLS. | USPAT; US-PGPUB | 2002/05/07 18:12 |
| - | 117 | (118/723an).CCLS. | USPAT; US-PGPUB | 2002/05/07 18:12 |
| - | 136 | 118/723i.ccls. and 156/345.48.ccls. | USPAT; EPO; JPO | 2002/05/08 11:30 |
| - | 41 | (118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and ((Faraday adj shield)) | USPAT; EPO; JPO | 2002/05/08 11:31 |
| - | 10 | ("4659449" "5105761" "5134965" "5290993" "5401350" "5415728" "5522934" "5614055" "5753044" "5777289").PN. | USPAT | 2002/05/08 11:50 |
| - | 5 | ("5681418" "5688357" "5688358" "5753044" "5777289").PN. | USPAT | 2002/05/08 11:52 |
| - | 192 | (118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and (shield (Faraday adj shield)) | USPAT; EPO; JPO | 2002/05/08 11:57 |
| - | 59310 | heat near5 (chamber reactor) | USPAT; EPO; JPO | 2002/05/08 13:21 |
| - | 1 | ((resist\$3 adj heat\$3) near5 (chamber reactor)) and ((118/723i.ccls. or 156/345.48.ccls. or 118/723an.ccls.) and (shield (Faraday adj shield))) | USPAT; EPO; JPO | 2002/05/08 13:23 |
| - | 384 | (resist\$3 adj heat\$3) near5 (chamber reactor) | USPAT; EPO; JPO | 2002/05/08 14:31 |
| - | 125 | (resist\$3 adj heat\$3) near5 (chamber reactor) and (vapor adj deposition) | USPAT; EPO; JPO | 2002/05/08 13:29 |
| - | 259 | ((resist\$3 adj heat\$3) near5 (chamber reactor)) not ((resist\$3 adj heat\$3) near5 (chamber reactor) and (vapor adj deposition)) | USPAT; EPO; JPO | 2002/05/08 14:05 |
| - | 12 | 4484063.URPN. | USPAT | 2002/05/08 14:22 |
| - | 165 | (heat\$3 adj wire) near5 (chamber reactor) | USPAT; EPO; JPO | 2002/05/08 14:33 |
| - | 164 | ((heat\$3 adj wire) near5 (chamber reactor)) not ((resist\$3 adj heat\$3) near5 (chamber reactor)) | USPAT; EPO; JPO | 2002/05/08 16:03 |
| - | 1440 | 118/724.ccls. | USPAT; EPO; JPO | 2002/05/08 16:21 |
| - | 30 | 118/724.ccls. and (heat\$3 adj wire) | USPAT; EPO; JPO | 2002/05/09 08:49 |
| - | 12 | 4958592.URPN. | USPAT | 2002/05/08 16:17 |
| - | 20 | 118/724.ccls. and 118/723i.ccls. | USPAT; EPO; JPO | 2002/05/08 16:49 |
| - | 6 | ("5001113" "5365057" "5401350" "5556501" "5614055" "5865896").PN. | USPAT | 2002/05/08 16:37 |
| - | 1085 | c23c016/48.ipc. | EPO; JPO | 2002/05/08 16:56 |
| - | 4 | c23c016/48.ipc. and ((heat\$3 adj wire) (resistive adj heat) (resist\$ adj heat)) | EPO; JPO | 2002/05/08 16:51 |
| - | 15 | c23c016/48.ipc. and "applied materials".as. | EPO; JPO | 2002/05/08 16:57 |
| - | 4 | 5690050.URPN. | USPAT | 2002/05/08 17:17 |
| - | 317 | 118/724.ccls. and (((heat\$3 adj element)(resist\$3 adj heat\$3) heat) near5 (chamber reactor)) | USPAT; EPO; JPO | 2002/05/09 10:09 |
| - | 109 | 156/345.37.ccls. | USPAT; EPO; JPO | 2002/05/09 10:24 |
| - | 114 | 156/345.37.ccls. | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 14:22 |
| - | 1963 | 118/725.ccls. | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 14:23 |

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|---|-------|--|---------------------------------|------------------|
| - | 23 | 118/725.ccls. and ((resist\$3 adj heat) (heat\$3 adj wire) near5 (substrate workpiece wafer)) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 14:26 |
| - | 6 | 118/725.ccls. and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer)) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 14:30 |
| - | 389 | (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer)) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 16:28 |
| - | 2 | (h011021/\$.ipc. and c23c016/\$.ipc.) and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer)) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 14:41 |
| - | 11 | c23c016/\$.ipc. and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer)) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 14:43 |
| - | 53 | (h011021/\$.ipc.) and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer)) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 14:55 |
| - | 7941 | (substrate workpiece wafer) adj conductive | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 16:30 |
| - | 26835 | (substrate workpiece wafer) near conductive | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 16:29 |
| - | 85726 | vapor adj deposition | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 16:30 |
| - | 3206 | (vapor adj deposition) and ((substrate workpiece wafer) near conductive) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 16:30 |
| - | 2 | 156/345.48 and ((substrate workpiece wafer) adj conductive) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 16:31 |
| - | 9 | 156/345.48 and ((substrate workpiece wafer) near conductive) | USPAT; US-PGPUB; EPO; JPO | 2002/05/09 16:31 |